A	2016-3				
B	2019-4-12		RθJA=625 SOT363-6L SOT-363		
C	2019-4-20				
D	2020-11-10				
E	2021-10-16	4			

/ Descriptions

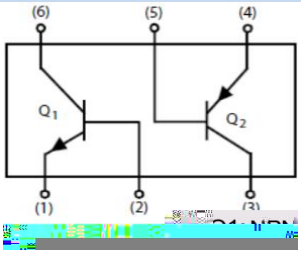
SOT-363

/ Features

h_{FE} $V_{CE(sat)}$

/ Applications

/ Equivalent Circuit



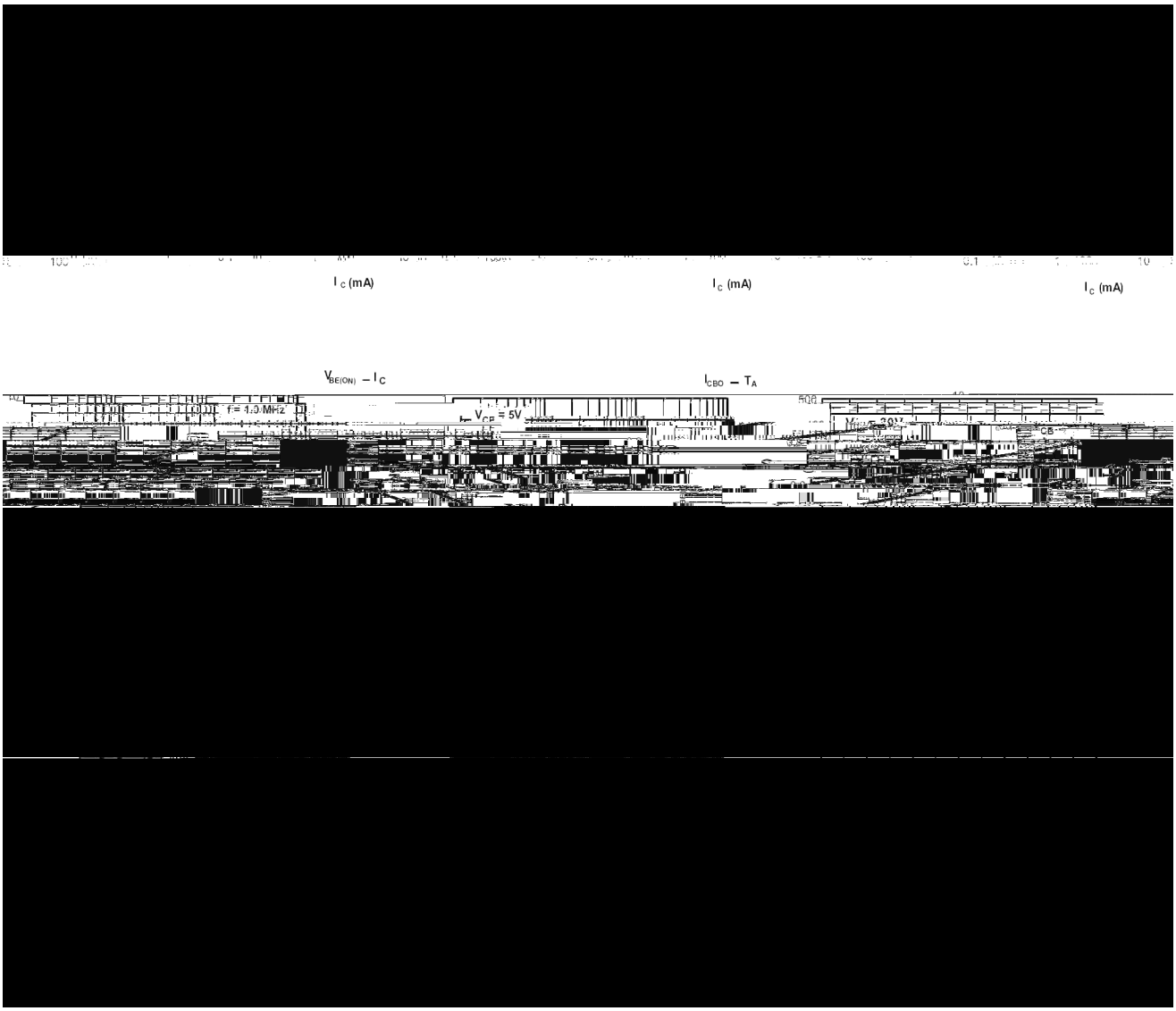
/ Pinning



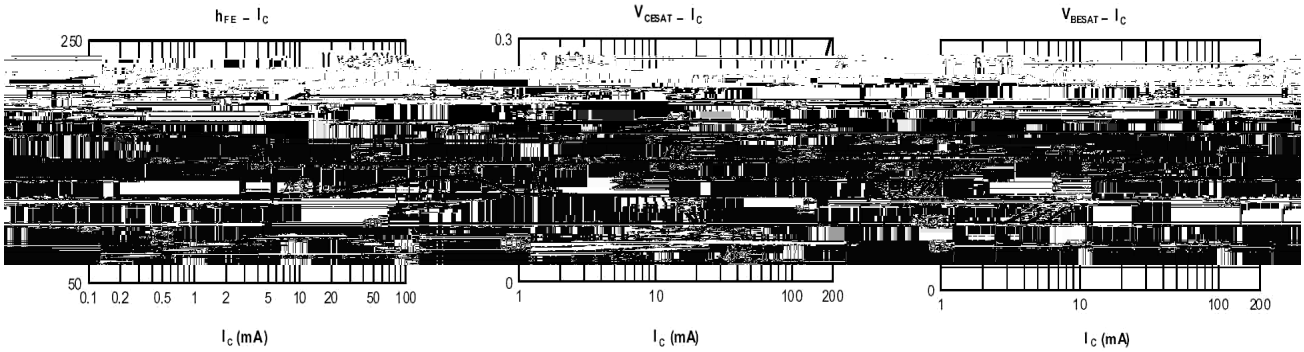
/ h_{FE} Classifications & Marking

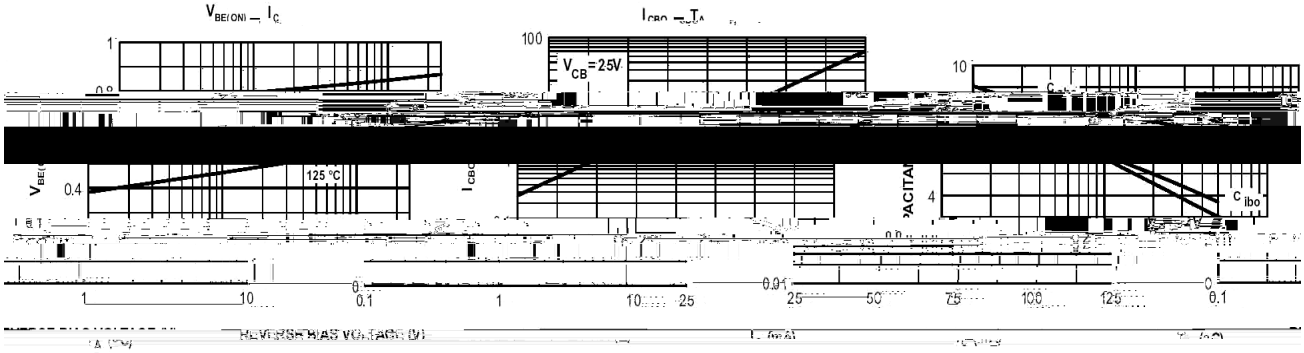
		~	

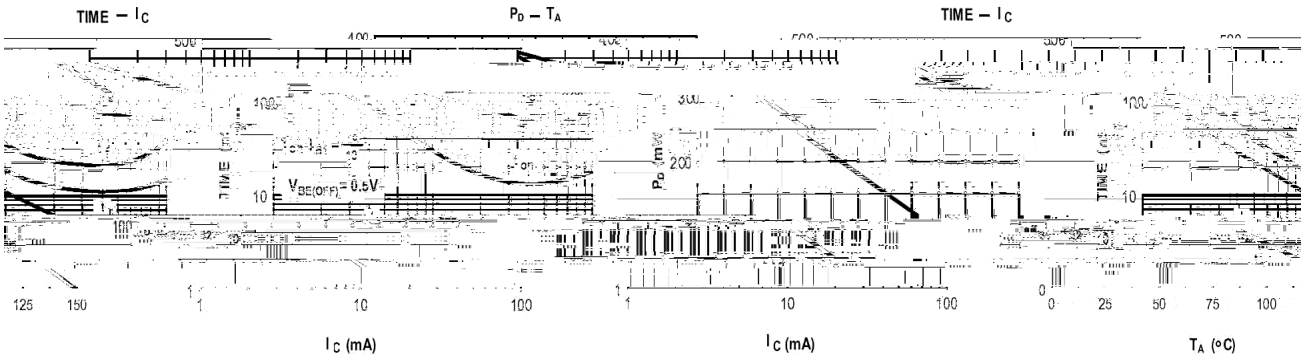
/ Electrical Characteristic Curve (NPN)



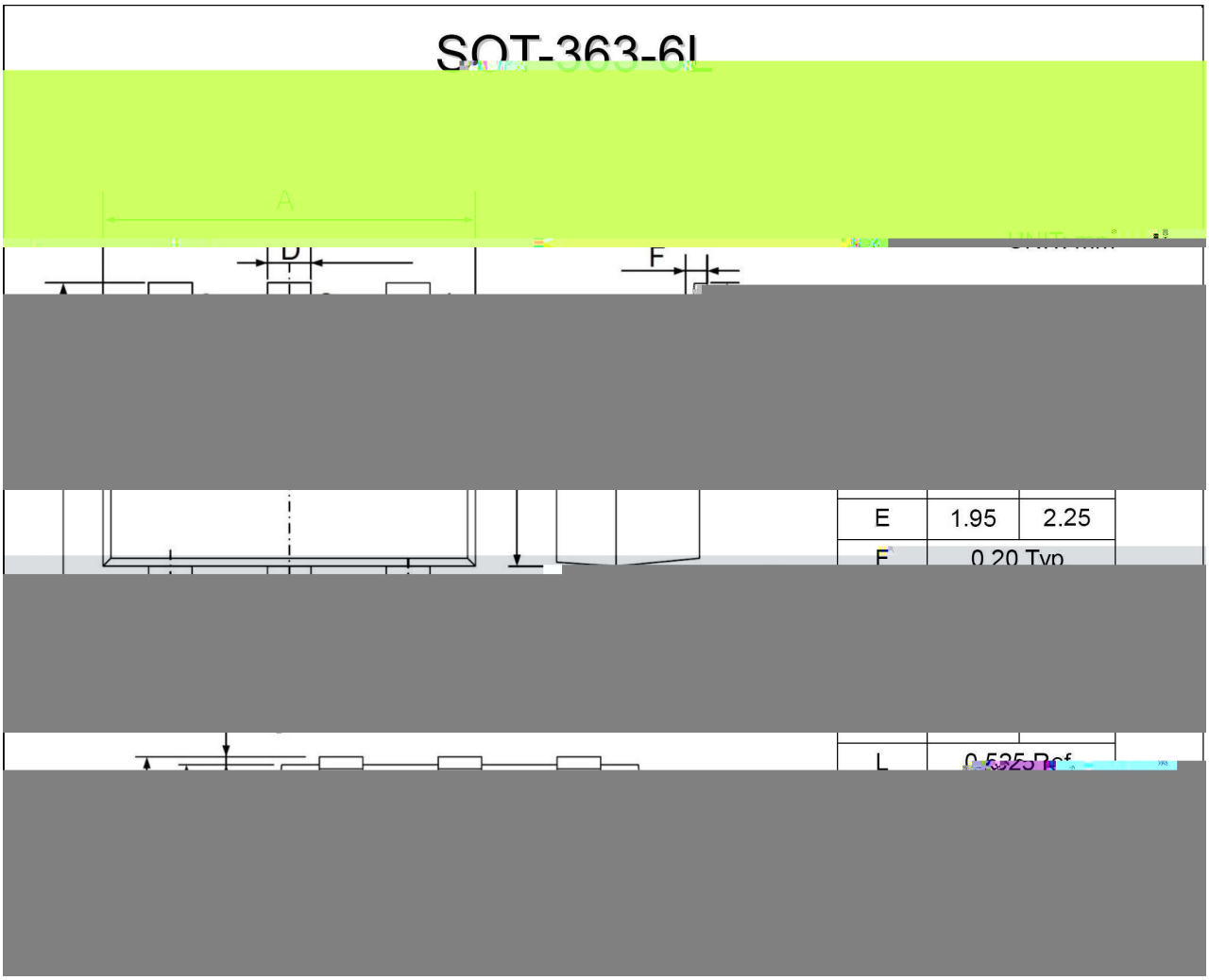
/ Electrical Characteristic Curve (PNP)







/ Package Dimensions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

包装数量 包装尺寸 :

封装形式